

EUROPEAN PATENT OFFICE

Patent Abstracts of Japan

PUBLICATION NUMBER : 06077299
PUBLICATION DATE : 18-03-94

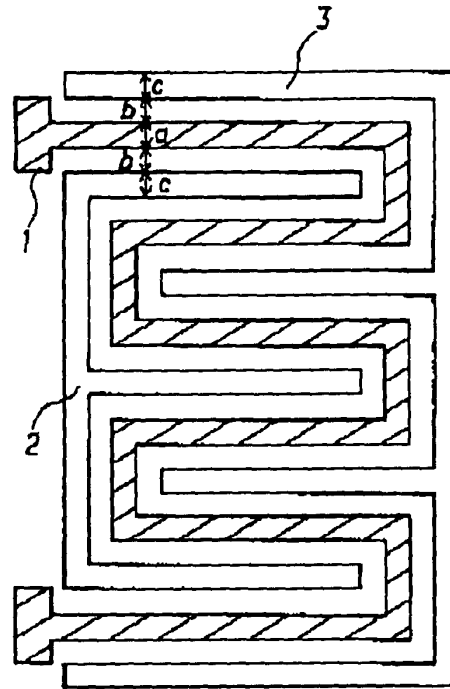
APPLICATION DATE : 25-08-92
APPLICATION NUMBER : 04225926

APPLICANT : KAWASAKI STEEL CORP;

INVENTOR : HORIKOSHI HIROSHI;

INT.CL. : H01L 21/66 G01R 31/02 G01R 31/26

TITLE : WIRING TEST OF SEMICONDUCTOR
DEVICE



ABSTRACT : PURPOSE: To provide a method for testing wirings of a semiconductor device which preferably evaluates resistivity to electro-migration without receiving influence of Joule heat.

CONSTITUTION: Only electro-migration can be evaluated by providing dummy wirings 2, 3 in both sides of a test wiring 1 on a wafer and radiating the Joule heat generated by stress applied to the test wiring 1 through the dummy wirings 2, 3.

COPYRIGHT: (C)1994,JPO&Japio

→ see Blind structure